



CBR-SMD RF COG, Ceramic, 3.9 pF, +/-0.1 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



General Information		
Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	12.03 mg	
Notes	Solder Wave or Solder Reflow.	
Shelf Life	78 Weeks	
MSL	1	

3.9 pF

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

L	2mm +/-0.2mm	Tolerance	+/-0.1 pF
W	1.25mm +/-0.2mm	Voltage DC	250 VDC
Т	0.85mm +/-0.1mm	Dielectric Withstanding Voltage	500 VDC
В	0.5mm +/-0.2mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.209%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms
		Quality Factor	478

Specifications Capacitance

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